



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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企业微信二维码



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Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
30V	3.8mΩ @ V _{GS} = 10V	145A
	6mΩ @ V _{GS} = 4.5V	115A

Features and Benefits

- Low R_{DS(ON)} – Minimizes On-State Losses
- Excellent Q_{gd} x R_{DS(ON)} Product (FOM)
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- 100% Unclamped Inductive Switching – Ensures More Reliability
- Rated to +175°C – Ideal for High Ambient Temperature Environments

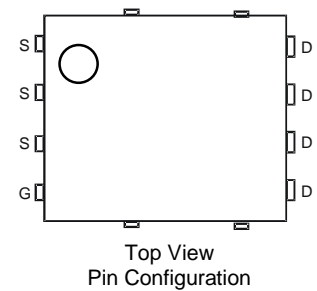
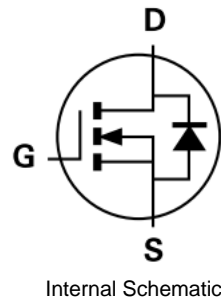
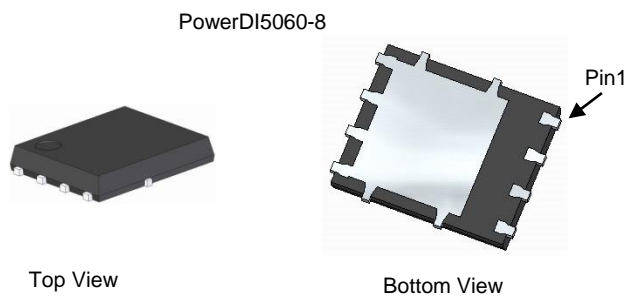
Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Backlighting
- Power Management Functions
- DC-DC Converters

Mechanical Data

- Case: PowerDI®5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish — Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.097 grams (Approximate)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	30	V
Gate-Source Voltage	V _{GSS}	+20 -16	V
Continuous Drain Current (Note 5)	I _D	T _A = +25°C	22
		T _A = +100°C	16
Continuous Drain Current (Note 6)	I _D	T _C = +25°C	145
		T _C = +100°C	103
Maximum Continuous Body Diode Forward Current	I _S	100	A
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)	I _{DM}	180	A
Avalanche Current, L=0.3mH	I _{AS}	27	A
Avalanche Energy, L=0.3mH	E _{AS}	110	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation	P _D	136	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	47	°C/W
Thermal Resistance, Junction to Case (Note 6)	R _{θJC}	1.1	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 24V, V _{GS} = 0V
Zero Gate Voltage Drain Current (Note 8)	I _{DSS}	—	—	10	μA	V _{DS} = 24V, V _{GS} = 0V T _J = +125°C
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = +20V, V _{DS} = 0V V _{GS} = -16V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1	1.6	3	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	3.3	3.8	mΩ	V _{GS} = 10V, I _D = 20A
		—	5	6		V _{GS} = 4.5V, I _D = 7A
Diode Forward Voltage	V _{SD}	—	0.70	1	V	V _{GS} = 0V, I _S = 1A
DYNAMIC CHARACTERISTICS						
Input Capacitance (Note 8)	C _{ISS}	—	2370	—	pF	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz
Output Capacitance (Note 8)	C _{OSS}	—	1360	—		
Reverse Transfer Capacitance (Note 8)	C _{RSS}	—	240	—		
Gate Resistance	R _g	0.14	0.7	1.75	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
SWITCHING CHARACTERISTICS (Note 8)						
Total Gate Charge (V _{GS} = 10V)	Q _g	—	43.7	—	nC	V _{DS} = 15V, I _D = 20A
Gate-Source Charge	Q _{gs}	—	6.9	—		
Gate-Drain Charge	Q _{gd}	—	8	—		
Turn-On Delay Time	t _{D(ON)}	—	6.2	—	ns	V _{DD} = 15V, V _{GS} = 10V, R _G = 3Ω, R _L = 0.75Ω
Turn-On Rise Time	t _R	—	4.2	—		
Turn-Off Delay Time	t _{D(OFF)}	—	21	—		
Turn-Off Fall Time	t _F	—	8	—		
Body Diode Reverse Recovery Time	t _{RR}	—	25	—	ns	I _F = 15A, dI/dt = 500A/μs
Body Diode Reverse Recovery Charge	Q _{RR}	—	37	—	nC	

- Notes:
- Device mounted with exposed drain pad on 25mm by 25mm 2oz copper on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady state.
 - Thermal resistance from junction to soldering point (on the exposed drain pad).
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

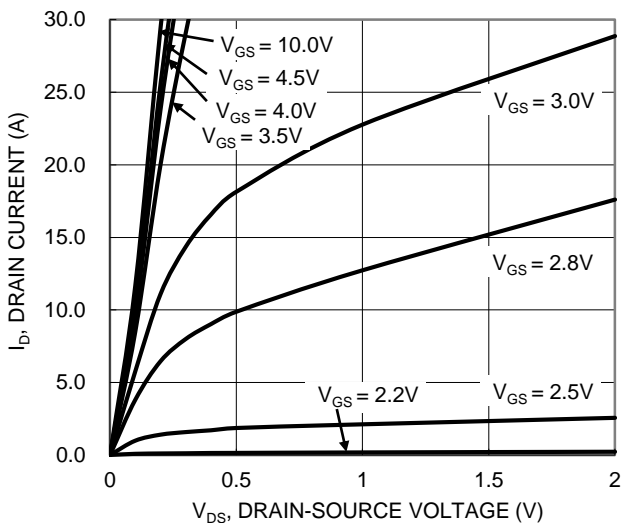


Figure 1. Typical Output Characteristic

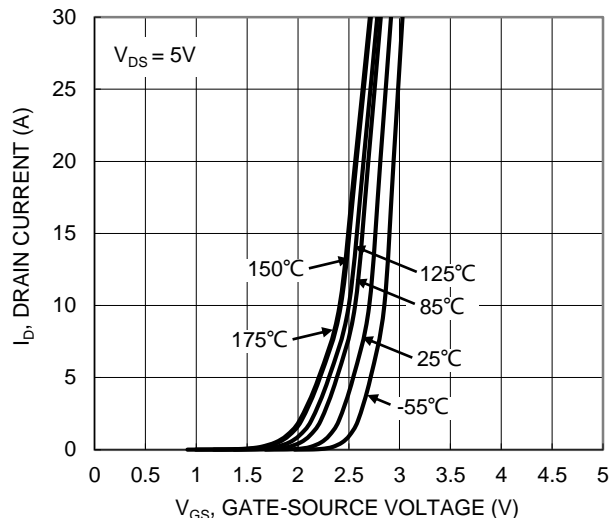


Figure 2. Typical Transfer Characteristic

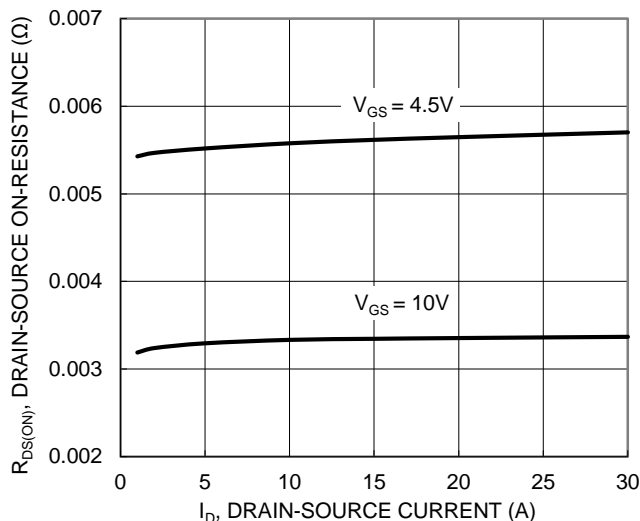


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

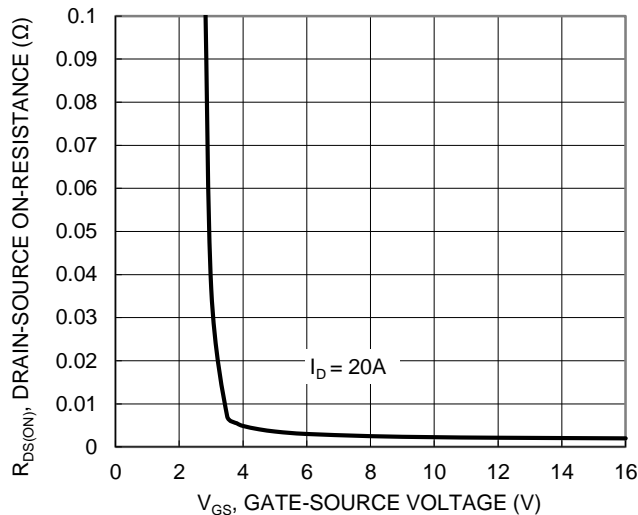


Figure 4. Typical Transfer Characteristic

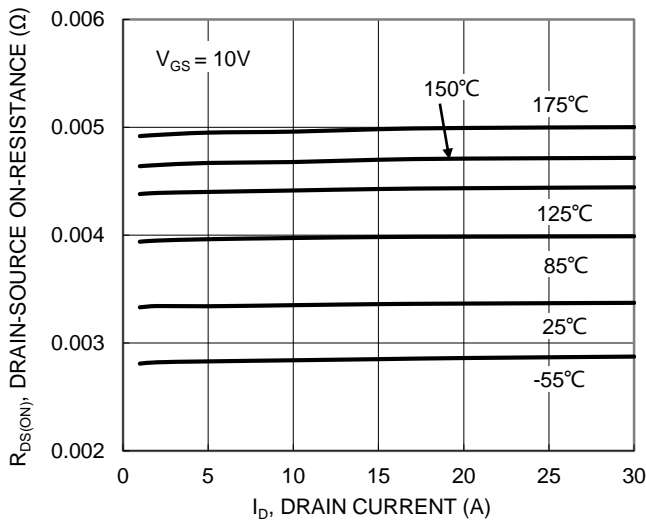


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

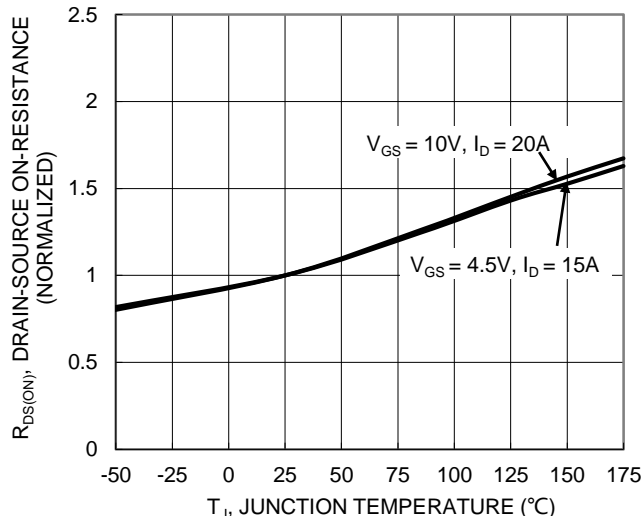


Figure 6. On-Resistance Variation with Junction Temperature

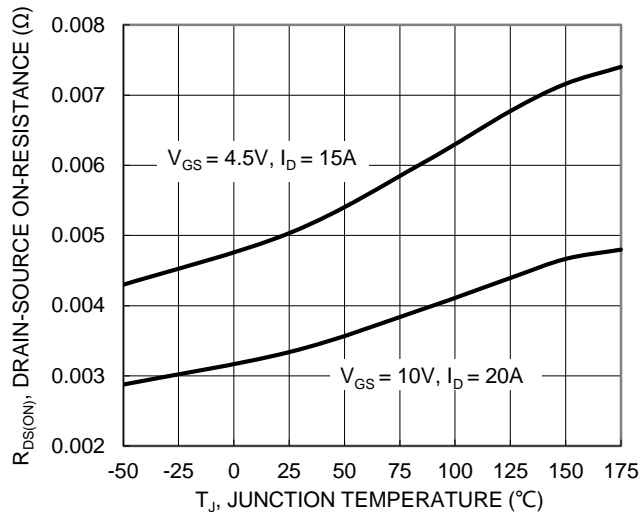


Figure 7. On-Resistance Variation with Junction Temperature

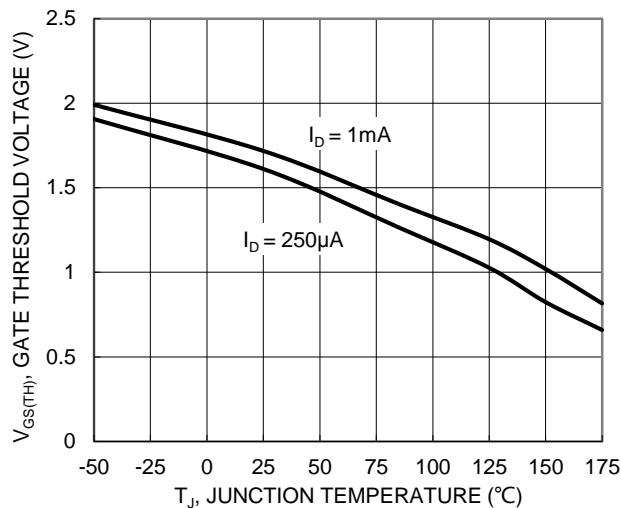


Figure 8. Gate Threshold Variation vs. Junction Temperature

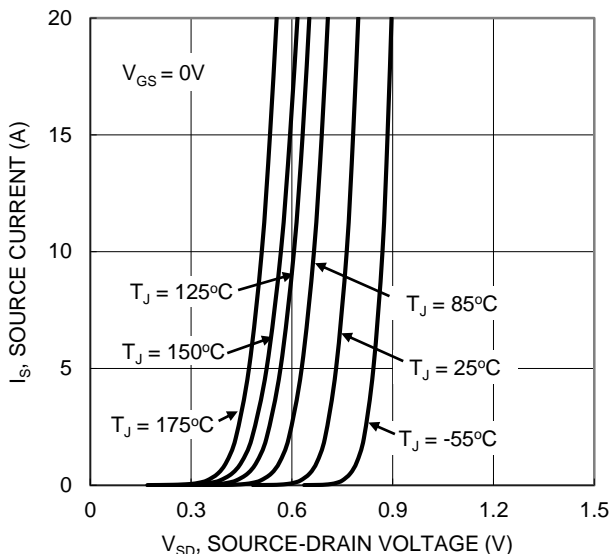


Figure 9. Diode Forward Voltage vs. Current

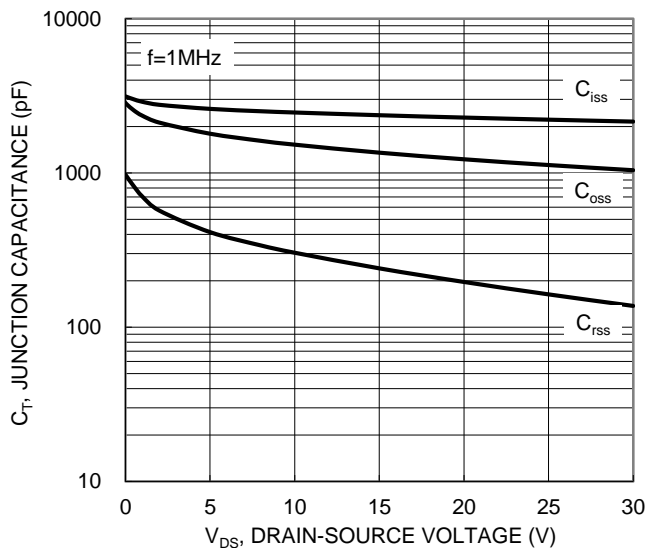


Figure 10. Typical Junction Capacitance

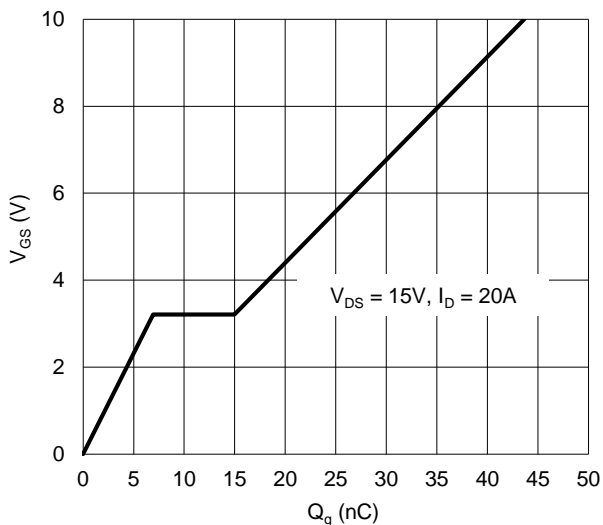


Figure 11. Gate Charge

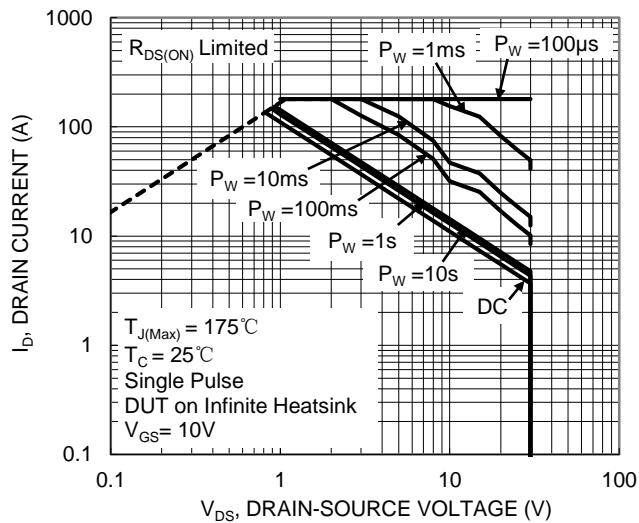


Figure 12. SOA, Safe Operation Area

